



Initial Product/Process Change Notification

Document #: IPCN22951Y

Issue Date: 05 Dec 2019

Title of Change:	E7100: Transfer of the bumping process from Amkor to ASEKH.										
Proposed First Ship date:	20 Oct 2020 or earlier if approved by customer										
Contact Information:	Contact your local ON Semiconductor Sales Office or Ivo.Rotthier@onsemi.com										
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.										
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>										
Marking of Parts/ Traceability of Change:	By date code										
Change Category:	Assembly Change										
Change Sub-Category(s):	Manufacturing Site Transfer										
Sites Affected:											
ON Semiconductor Sites	External Foundry/Subcon Sites										
None	AMKOR, Taiwan T5										
	ASEKH, Taiwan (Kaohsiung)										
Description and Purpose:											
	<table border="1"> <thead> <tr> <th></th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Bump Location</td> <td>AMKOR, Taiwan T5</td> <td>ASEKH, Taiwan (Kaohsiung)</td> </tr> <tr> <td>Bump composition</td> <td>SnAg (Ag = 2.3%)</td> <td>SnAg (Ag = 1.8%)</td> </tr> </tbody> </table>			Before Change Description	After Change Description	Bump Location	AMKOR, Taiwan T5	ASEKH, Taiwan (Kaohsiung)	Bump composition	SnAg (Ag = 2.3%)	SnAg (Ag = 1.8%)
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Bump Location	AMKOR, Taiwan T5	ASEKH, Taiwan (Kaohsiung)									
Bump composition	SnAg (Ag = 2.3%)	SnAg (Ag = 1.8%)									
There is no product marking change as a result of this change.											

**Qualification Plan:**

QV DEICE NAME: E7100-102WC66-AG

PACKAGE: WLCSP

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta = 125°C, bias 2V, on TQFP coupon	504 hrs
HTSL	JESD22-A103	Ta=150°C, inspection only	504 hrs
TC	JESD22-A104	Ta = -55°C to + 125°C, inspection only	500 cyc
HAST	JESD22-A110	130°C, 85% RH. 18.8 psig, bias 2V, on TQFP coupon	96 hrs
UHAST	JESD22-A118	130°C, 85% RH. 18.8 psig, unbiased, inspection only	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C inspection only	3X

Estimated date for qualification completion: 31 January 2020

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
E7100-102WC66-AG	E7100-102WC66-AG
E7100-102WC66-BG	E7100-102WC66-AG